

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7300449

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HITOSHI KAMOSHIDA	03/08/2022
HISAYUKI TAKASU	03/14/2022
ATSUSHI KAMINO	04/12/2022
SHOTA AIDA	02/21/2022
MEGUMI NAKAMURA	02/09/2022
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECH CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17637728
CORRESPONDENCE DATA	
Fax Number:	(202)628-8844
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2026242500
Email:	asaguros@crowell.com, edocket@crowell.com
Correspondent Name:	CROWELL & MORING LLP
Address Line 1:	1001 PENNSYLVANIA AVENUE, NW
Address Line 4:	WASHINGTON, D.C. 20004
ATTORNEY DOCKET NUMBER:	109701.PF325US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	04/27/2022
Total Attachments: 5	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Tech Corporation, a corporation organized under the laws of Japan, located at 17-1, Toranomon 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Tech Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ION MILLING DEVICE AND MILLING PROCESSING METHOD USING SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Tech Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Tech Corporation,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Hitoshi KAMOSHIDA</u> Hitoshi Kamoshida	<u>3 / 8 / 2022</u>
2)	<u>Hisayuki TAKASU</u>	
3)	<u>Atsushi KAMINO</u>	
4)	<u>Shota AIDA</u>	
5)	<u>Megumi NAKAMURA</u>	
6)		
7)		
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10)		

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2) <u>Hisayuki TAKASU</u> <i>Hisayuki Takasu</i>	<u>3/14 / 2022</u>
3) <u>Atsushi KAMINO</u>	_____
4) <u>Shota AIDA</u>	_____
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1) <u>Hitoshi KAMOSHIDA</u>	_____
2) <u>Hisayuki TAKASU</u>	_____
3) <u>Atsushi KAMINO</u> <i>Atsushi Kamino</i>	_____ <i>4 / 12 / 2022</i>
4) <u>Shota AIDA</u>	_____
5) <u>Megumi NAKAMURA</u>	_____
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3) <u>Atsushi KAMINO</u>	_____
4) <u>Shota AIDA</u> <i>Shota Aida</i>	_____ <i>2/21/2022</i>
5) <u>Megumi NAKAMURA</u>	_____
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4)	<u>Shota AIDA</u>	_____
5)	<u>Megumi NAKAMURA</u> <i>Megumi Nakamura</i>	<u>2/9/2022</u>
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____